

DECLARATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name; that

I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named below) of the invention entitled:

**MACROCAPSULES CONTAINING
MICROENCAPSULATED PHASE CHANGE MATERIALS,**

described and claimed

X in the attached specification;
 in the specification filed _____,
 as U.S. Application Serial No. _____,
 and as amended _____.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims as filed and as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

PRIORITY CLAIM

I hereby claim foreign priority benefits under title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

<u>Prior Foreign Application(s)</u>	<u>Priority Claimed</u>
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number	Country	Day/Mo/Yr	Yes	No
number	Country	Day/Mo/Yr	Yes	No

I hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below.

_____ Application No.	_____ Filing Date
60/235,850	September 27, 2000
	Filing Date
_____ Application No.	_____ Filing Date

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status
Application Serial No.	Filing Date	Status

Send Correspondence To:

Mark P. Levy
Thompson Hine LLP
2000 Courthouse Plaza N.E.
10 West Second Street, Dayton, Ohio 45402-1758

Direct Telephone Calls To:

Mark P. Levy
(937) 443-6949

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full name of sole or first Inventor – Danny Allen Davis

Inventor's Signature _____ Date _____

Residence: 4245 Casstown Clark Road, Casstown, Ohio 45312

Citizenship: U.S.A.

Post Office Address: Microtek Laboratories, Inc.

5747 Executive Blvd
Dayton, Ohio 45424-1448

Full name of second Inventor – Ronald Lee Hart

Inventor's Signature _____ Date _____

Residence: 1519 Heatherwood Trail, Xenia, Ohio 45385

Citizenship: U.S.A.

Post Office Address: Microtek Laboratories, Inc.
5747 Executive Blvd
Dayton, Ohio 45424-1448

Full name of sole or third Inventor – Dale Ellis Work

Inventor's Signature _____ Date _____

Residence: 115 North Madison Road, London, Ohio 43140

Citizenship: U.S.A.

Post Office Address: Microtek Laboratories, Inc.
5747 Executive Blvd
Dayton, Ohio 45424-1448

Full name of sole or fourth Inventor - David Russell Virgallito

Inventor's Signature _____ Date _____

Residence: 714 Springridge Place, Centerville, Ohio 45458

Citizenship: U.S.A.

Post Office Address: Microtek Laboratories, Inc.
5747 Executive Blvd
Dayton, Ohio 45424-1448